INVESTOR MEETING
2015 SANTA CLARA

Diane Bryant
Senior Vice President & General Manager
Data Center Group

KEY MESSAGES

Fundamental growth drivers remain strong

Adoption of cloud computing growing and transforming all segments

Non-CPU products contribute meaningful growth

*Forecast is based on current expectations given available information and is subject to change without notice
Source: Intel

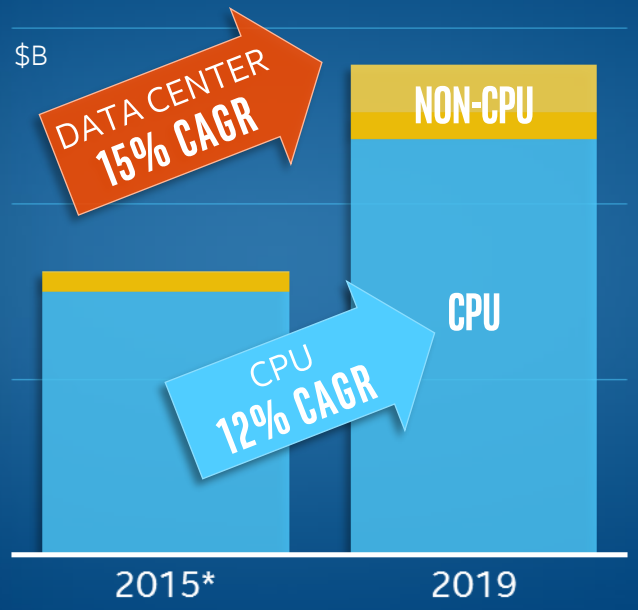
DATA CENTER GROWTH FORECAST

GROWTH BY END-USER SEGMENT

2015-2019*

COMMS SP	>20% CAGR
CLOUD SP	>20% CAGR
GOVERNMENT, ACADEMIA, SCIENCE	~20% CAGR
ENTERPRISE IT	<5% CAGR

CONTRIBUTION OF NON-CPU



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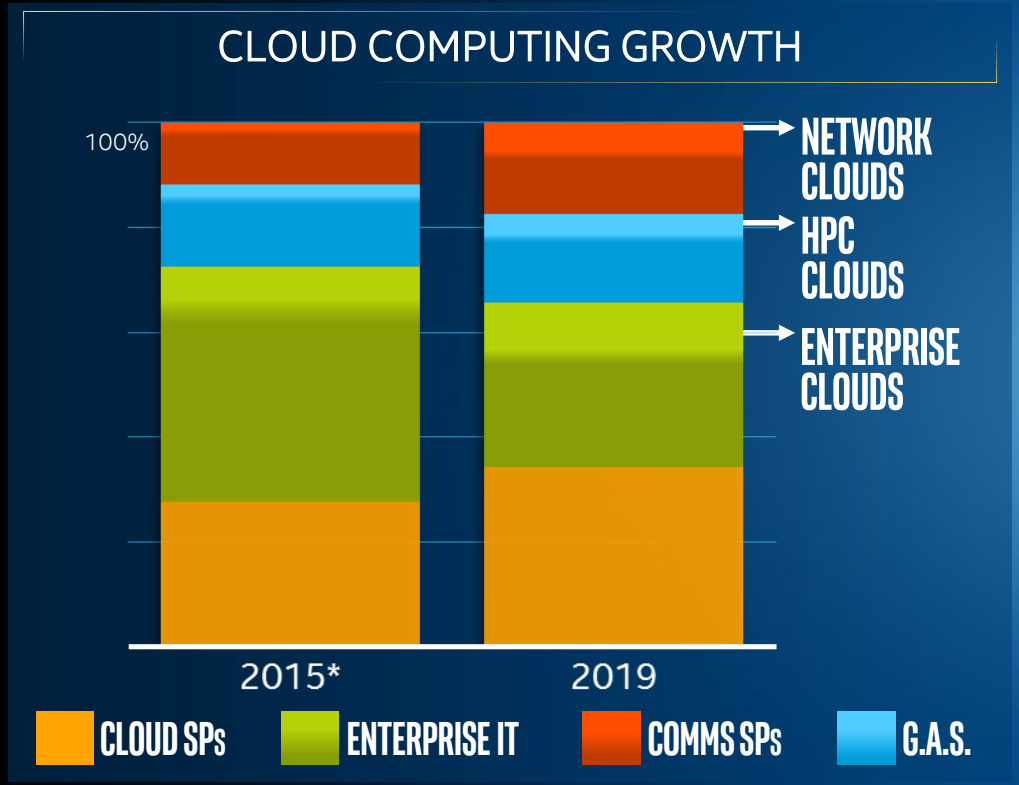
ADOPTION OF CLOUD COMPUTING ACROSS ALL SEGMENTS



Accelerated technology adoption

TAM expansion

ASP uplift

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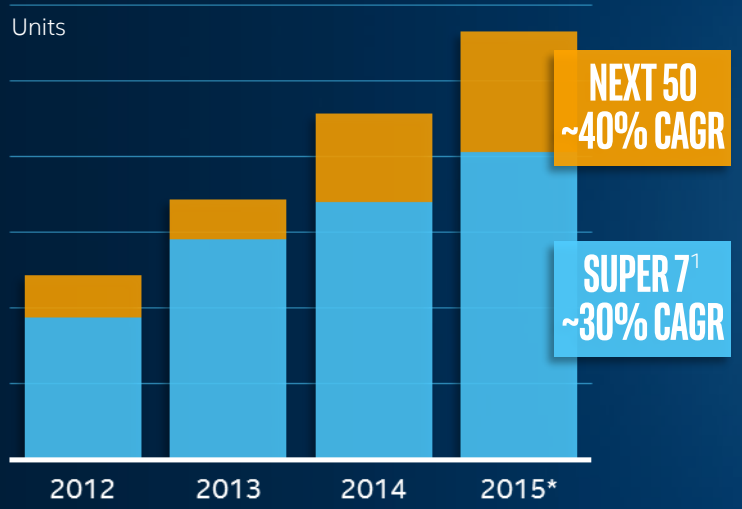
DIVERSIFICATION OF THE CLOUD SERVICE PROVIDER MARKET

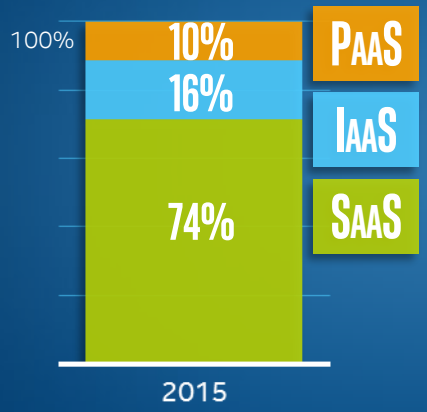
CLOUD SP GROWTH

Cloud SP CPU Units



"AS A SERVICE" DYNAMICS

2015 Revenue[2]



GROWTH OUTSIDE U.S.

1H'15 YoY Growth[3]

Americas **46%**

Europe & Middle East **57%**

Asia **55%**

1. Super 7= Alibaba, Amazon, Baidu, Facebook, Google, Microsoft, Tencent
2. Source: IDC: Worldwide SaaS and Cloud Software 2015-2019 Forecast and 2014 Vendor Shares, August 2015
3. Source: 1H'14-15 YoY growth based on top 41 CSPs in each region. Technology Business Research, Public Cloud Benchmark 2Q15

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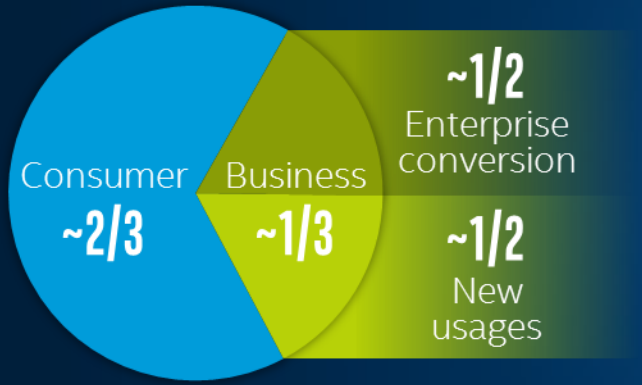
CLOUD SERVICE PROVIDER DYNAMICS

CONSUMER vs. BUSINESS

2015 Volume[1]



SUPER 7 VALUE PERFORMANCE

5 have custom CPUs

7 bought higher price point SKUs

5 are in the Early Ship Program

4 will sample FPGAs in Q1'16

2 have sampled Silicon Photonics

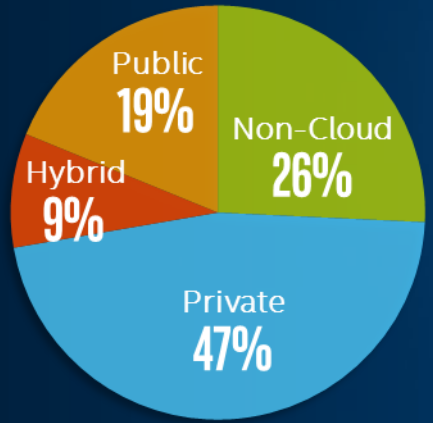
BROAD interest in 3D XPoint™

1. Source: Intel estimate

CLOUD ENABLES NEW ENTERPRISE GROWTH

PRIVATE CLOUD INVESTMENTS

Expected workload destination[1]
2015-2016



ENABLING NEW BUSINESSES[2]

Delivering an **end-to-end connected car** lifestyle through BMW Connected Drive

Making **industrial analytics** applications easier to deploy with Predix Cloud

Improving **first responder safety** through cloud connected devices

Enabling **precision farming** through cloud-based analytics

1. Source: 451 Research, Voice of the Enterprise Cloud Computing Advisory Report Q4 2014 Survey of 1200 Senior IT leaders / decision makers (N=370)
2. Source: Company reports

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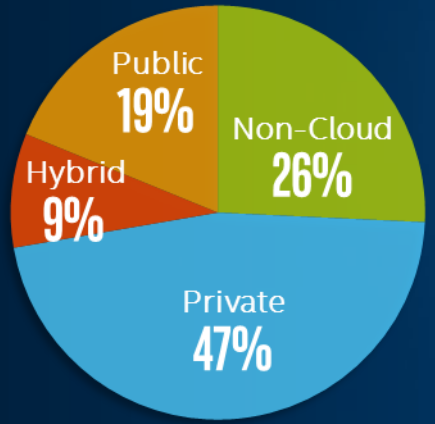

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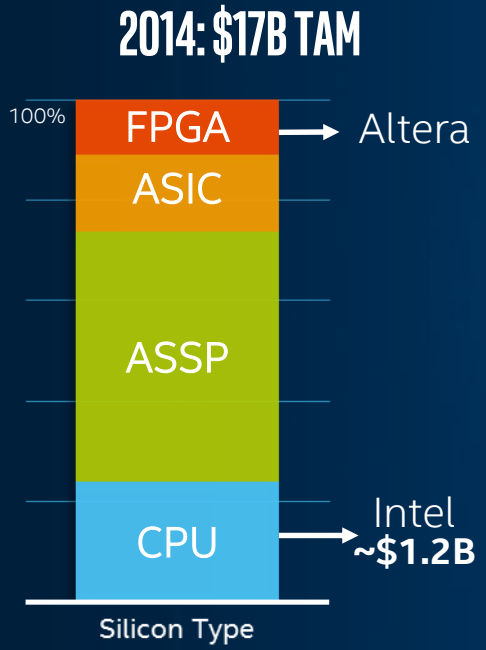
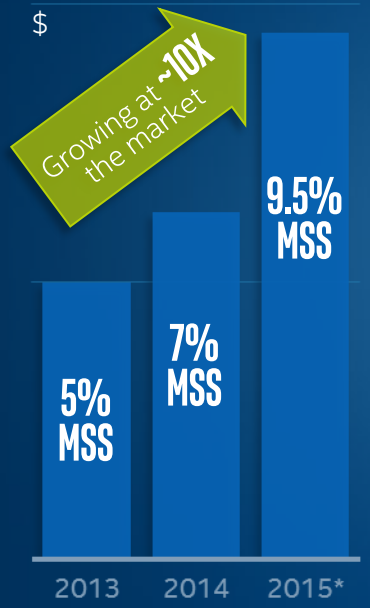
NETWORK MOVES TO CLOUD

NETWORK OPPORTUNITY[1]



IA MSS[2]



NFV DEPLOYED ON INTEL ARCHITECTURE

at&t

SK telecom

verizon

vodafone

VALUE TO SERVICE PROVIDERS

50% OpEx & power reduction[3]
-China Mobile

97% reduction in time to deployment of new services[4]
-Telefonica

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1. Source: IHS, Company reports, Intel analysis
2. Source: Intel
3. Source: China Mobile CRAN whitepaperSource: IHS, company reports, Intel analysis
4. Source: Telefonica UNICA, http://saladeprensa.telefonica.com/documentos/UNICA__20140224.pdf

DELIVERING NEW PRODUCTS

INTEL SILICON PHOTONICS

Samples shipping

ONLY ON-DIE INTEGRATED LASER

Longest reach at **2 km**

Highest port density

>20% cost advantage

$5B TAM 2020[4]

INTEL OMNI-PATH ARCHITECTURE

1st production in December

LEADERSHIP VS. INFINIBAND EDR

10% performance advantage[1]

60% lower system power[2]

20% system cost savings[3]

$1.6B TAM 2020[5]

3D XPOINT™ DIMMS

Sampling in 2016

NEW CLASS OF NON-VOLATILE MEMORY

4X memory capacity

½ the cost of DRAM

$34B TAM 2020[6]

1. Tests performed on Intel® Xeon® Processor E5-2697v3 dual-socket servers with 2133 MHz DDR4 memory. Intel® Turbo Boost Technology enabled and Intel® Hyper-Threading Technology disabled. Intel OPA: Open MPI 1.10.0 with PSM2. Pre-production Intel Corporation Device 24f0 – Series 100 HFI ASIC, Series 100 Edge Switch – 48 port. IOU Non-posted Prefetch disabled in BIOS. EDR: Open MPI 1.8-mellanox released with hpcx-v1.3.336-icc-MLNX_OFED_LINUX-3.0-1.0.1-redhat6.6-x86_64.tbz. Mellanox EDR ConnectX-4 Single Port Rev 3 MCX455A HCA. Mellanox SB7700 - 36 Port EDR Infiniband switch. 17% claim: HPCC 1.4.3 Random order ring latency. 16 nodes, 28 MPI ranks per node. 7% message rate claim: Ohio State Micro Benchmarks v. 4.4.1. osu_mbw_mr 28 MPI ranks per node, 8 byte message.
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4. Intel estimate
5. IDC, Intel estimate. Includes HPC deployments only.
6. Source: Gartner, IHS, Intel analysis

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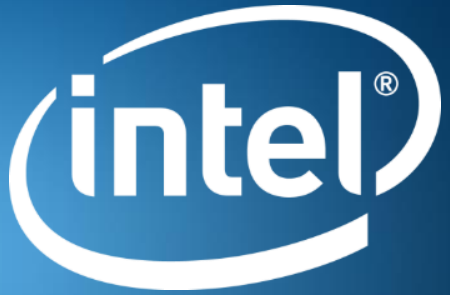

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